

# HVD144A

## Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G0429-0100  
(Previous: ADE-208-1591)  
Rev.1.00  
Nov 26, 2004

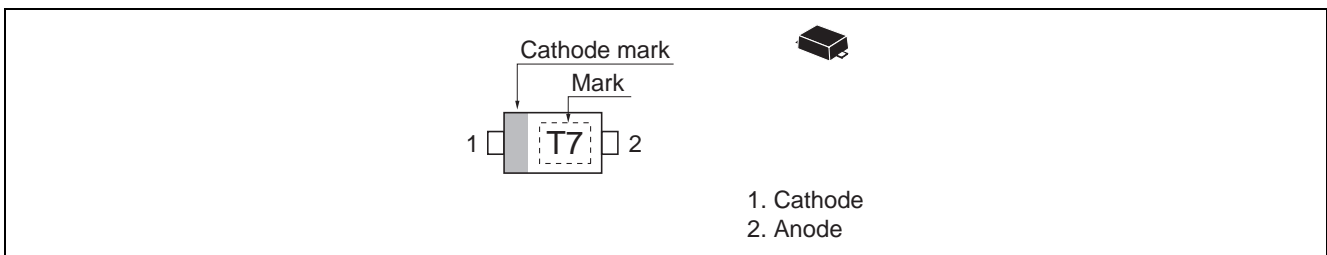
### Features

- Adopting the trench structure improves low capacitance.(C = 0.43 pF max)
- Low forward resistance. ( $r_f = 1.80 \Omega$  max)
- Low operation current.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Code
HVD144A	T7	SFP

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Reverse voltage	$V_R$	30	V
Forward current	$I_F$	100	mA
Power dissipation	$P_d$	150	mW
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	$I_R$	—	—	100	nA	$V_R = 30\text{ V}$
Forward voltage	$V_F$	—	—	0.90	V	$I_F = 2\text{ mA}$
Capacitance	C	—	—	0.43	pF	$V_R = 1\text{ V}, f = 1\text{ MHz}$
Forward resistance	$r_f$	—	—	1.80	$\Omega$	$I_F = 2\text{ mA}, f = 100\text{ MHz}$
ESD-Capability *1	—	100	—	—	V	C = 200 pF, R = 0 $\Omega$ , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ;  $I_R > 100\text{ nA}$  at  $V_R = 30\text{ V}$ 

2. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

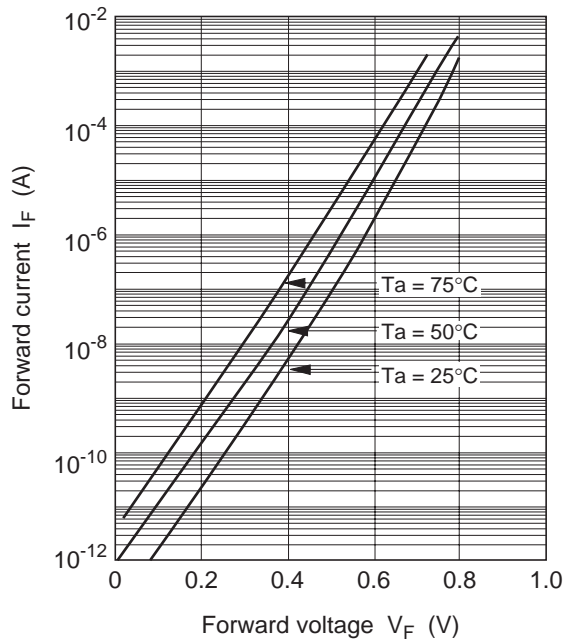


Fig.1 Forward current vs. Forward voltage

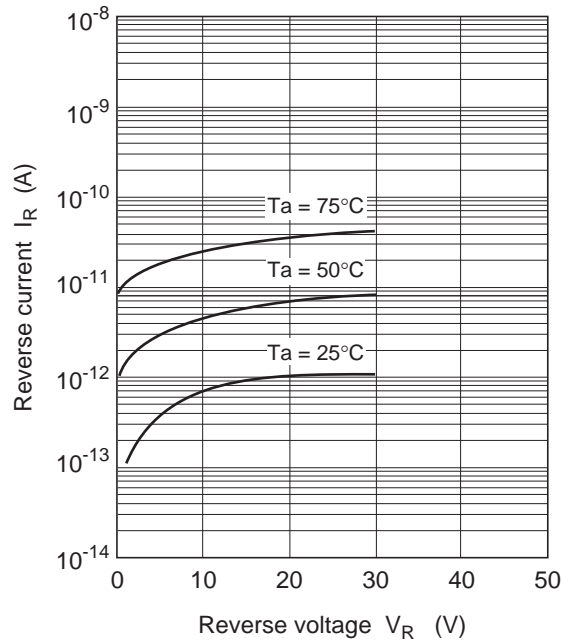


Fig.2 Reverse current vs. Reverse voltage

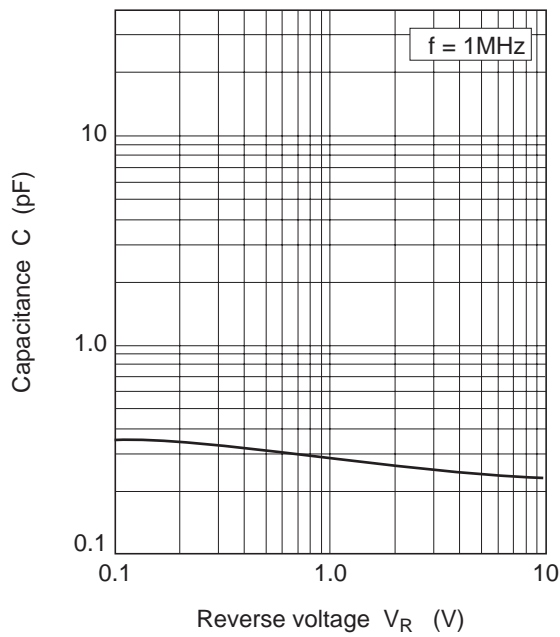


Fig.3 Capacitance vs. Reverse voltage

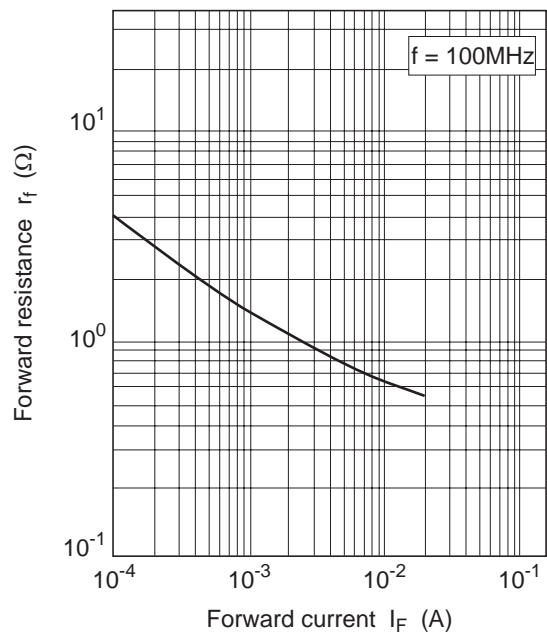


Fig.4 Forward resistance vs. Forward current

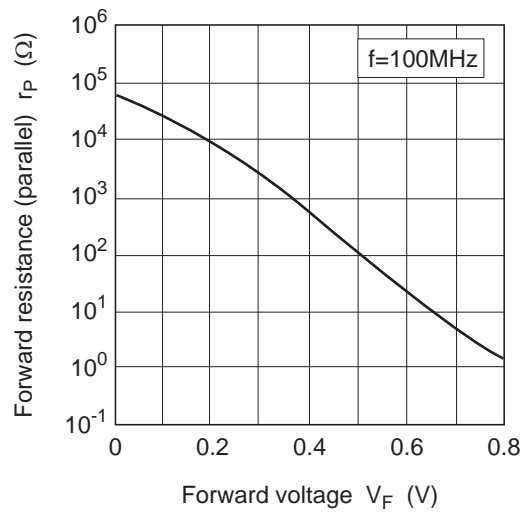
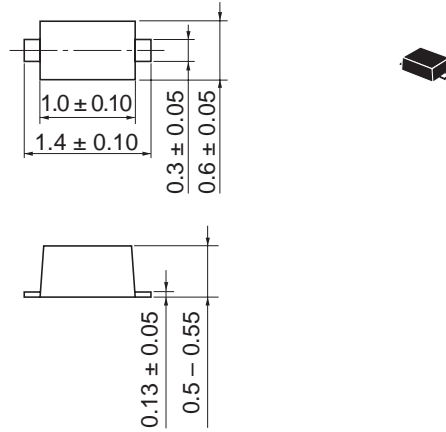


Fig.5 Forward resistance (parallel) vs. Forward voltage

## Package Dimensions

As of January, 2003  
Unit: mm

Package Code	SFP
JEDEC	—
JEITA	—
Mass (reference value)	0.0010 g

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